

In the Claims:

Claim 27 (currently amended). A process for producing a component, which comprises:

in a first working step, applying a first insulating layer having a layer thickness between 0.05 μm and 50 μm to a substrate;

in a second working step, applying a second insulating layer having a layer thickness between 0.05 μm and 50 μm and being chemically different from said at least one lower insulating layer and patterning the second insulating layer; and

in a third working step, activating a layer selected from the group consisting of the first insulating layer and the second insulating layer.

Claim 30 (currently amended). The process according to claim 29, which comprises patterning the first insulating layer, after the first working step.

Claim 31 (currently amended). The process according to claim 27, which comprises patterning the first insulating layer, after the first working step.